

SOT778-5

plastic thermal enhanced very thin quad flat package; no leads; 48 terminals; body 6 x 6 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN48
Package type industry code	HVQFN48
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	30-10-2002

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	[tbd]	-	6	[tbd]	mm
E	package width	[tbd]	-	6	[tbd]	mm
A ₂	package height	[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination	-	-	48	-	

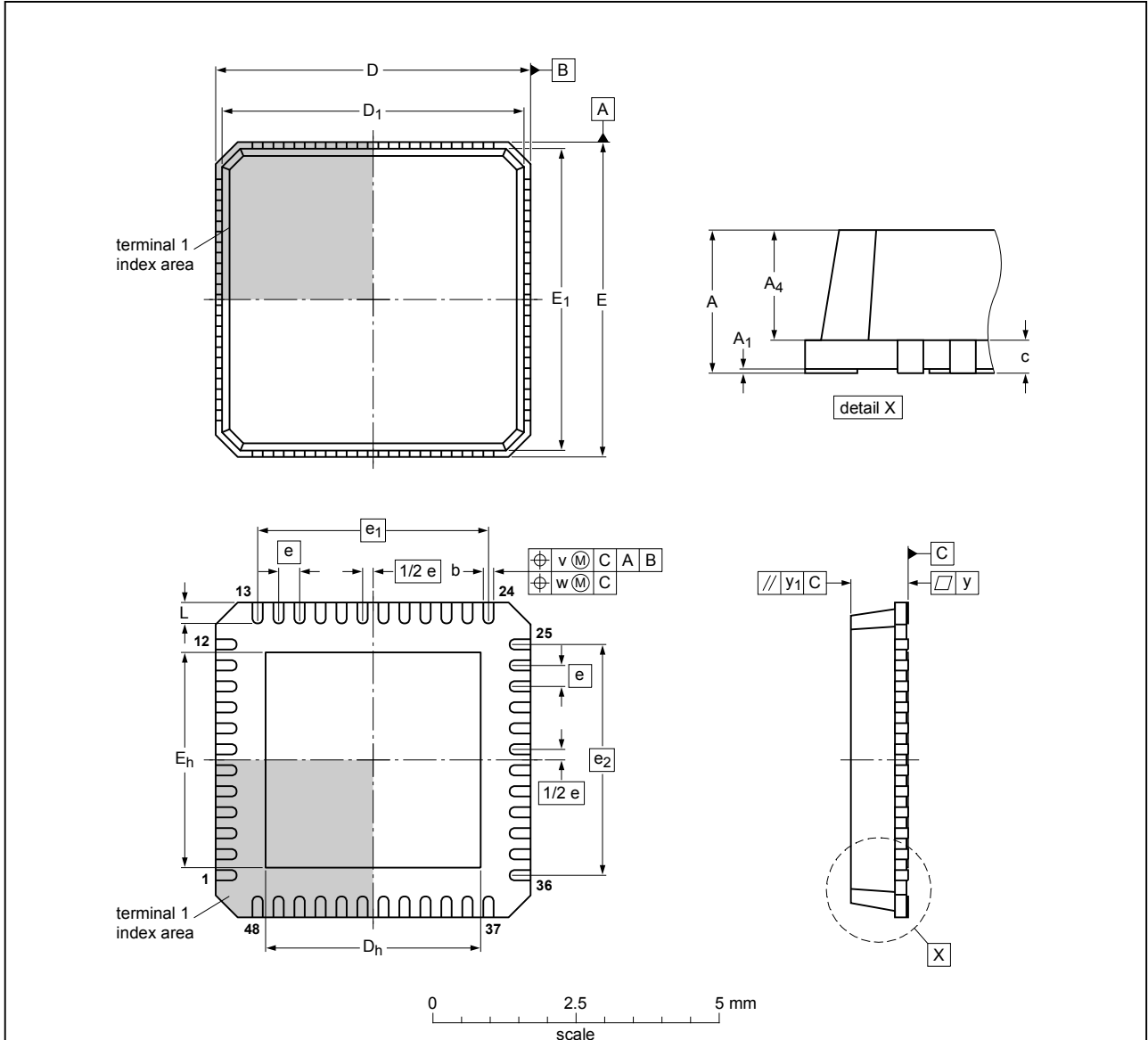


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2. Package outline

HVQFN48: plastic thermal enhanced very thin quad flat package; no leads; 48 terminals; body 6 x 6 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	A ₁	A ₄	b	c	D	D ₁	D _h	E	E ₁	E _h	e	e ₁	e ₂	L	v	w	y	y ₁
mm	1	0.05 0.00	0.80 0.65	0.25 0.15	0.2	6.1 5.9	5.85 5.65	4.25 3.95	6.1 5.9	5.85 5.65	4.25 3.95	0.4	4.4	4.4	0.5 0.3	0.1	0.05	0.05	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT778-5		---	---			05-10-25 05-10-31

Fig. 1. Package outline HVQFN48 (SOT778-5)

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3. Legal information

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